Performance Analysis of Low Power and High Speed CRC Generator Using group of D flip-flops based on 12T Memory Cell

M.Ananthi¹, P.Bharathi² and P.Manimekalai³

¹²Assistant Professor, Department of Electronics and Communication Engineering, Ariyalur Engineering College, Tamil Nadu, India.
¹UG Student, Department of Electronics and Communication Engineering, Ariyalur Engineering College, Tamil Nadu, India.

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ABSTRACT

The proposed implementation of a novel radiation-hardened-by-design (RHBD) high speed CRC Generator architecture using gate diffusion input technique. The main objective of CRC generator is used for error detection in communication systems. The Gate Diffusion Input logic is a technique that is used to reduce transistor count and power consumption of sequential circuits. The hardware component of CRC is consists of group of D flip-flops. Here the gate diffusion input logic based D flip-flop is a basic cell to design a CRC Generator, maintaining low complexity of logic design. The proposed architecture is validated by Tanner EDA tool and implementation on Spartan 6 FPGA development board series.

Keywords: Memory, CMOS, 12T model, power dissipation.

1. INTRODUCTION

MEMORIES are extensively used in aerospace applications as the medium to store data in which single event upsets (SEUs) induced by radiation particles are becoming one of the most significant issues. Because they can conduce to the data corruption in a memory chip and the circuit itself is not permanently damaged, SEUs are also described as the soft errors. Therefore, SEUs can cause a malfunctioning of an electronic system. In some critical memory applications (e.g., satellite equipment and cardioverter defibrillators, SEUs can be detrimental and crucial. However, radiation hardening techniques for memories are one of the bottlenecks in providing fault tolerance. For many years, some radiation-hardening-by-design (RHBD) techniques have been used to tolerate soft errors in memories using standard commercial CMOS foundry processes, with no modifications to the existing process or violation of design rules.

SRAM-based field-programmable gate arrays (FPGAs) have been widely used during the last decades. However, the volatility of SRAM has limited FPGAs in applications where high security and instant power-on are required. The problem can be solved by introducing non-volatile memory (NVM) as the configuration bit. However, the traditional NVM devices, such as anti-fuse, E2PROM, and flash, require high-voltage process and have poor logic compatibility, thus limiting the logic density and increasing the integration cost of FPGAs.

The remainder of this paper is mainly divided into the following sections. Section II introduces the proposed RHBD 12T cell structure and analysis. In Section III, simulations, and the detailed analysis of improved version is shown.

2. NOVEL RADIATION-HARDENED-BY-DESIGN (RHBD) 12T MEMORY CELL

The proposed RHBD 12T memory cell is shown in Fig. 1. Here, two access transistors, pMOS transistors P5 and P6, have been connected bit-lines BLN and BL to the output nodes QN and Q, respectively.
Considering the stored 1 state (i.e., QN = 0, Q = 1, S0 = 0, and S1 = 1) for the proposed RHBD 12T cell. When word-line WL is high state 1, transistors P1, P4, P7, N2, and N3 are ON, and the remaining transistors are OFF. Before read operation is executed in the proposed 12T memory cell, two bit-lines BL and BLN need to be recharged to supply voltage VDD. After read operation, and word-line WL is 0 state, the output node Q will store its original state 1 without changing. Fig. 2 shows a “write 0, read 0, write 1, and read 1” transient simulation result. From Fig. 2, we can see that the proposed cell can rightly achieve write and read operations.

Fig. 2. Transient simulation result of the proposed RHBD 12T cell

3. PERFORMANCE ANALYSIS OF LOW POWER AND HIGH SPEED CRC GENERATOR USING GROUP OF D FLIP-FLOPS

The basic GDI cell was used to design of combinational circuits and sequential circuit with less number of transistors and higher energy consumption as compare to conventional CMOS technique. A cyclic redundancy code can be calculated using one byte oriented method. Configurable CRC generator was implemented for error detection in communication using various software algorithms. The parallel CRC generator was completed designed using software approaches for increase the speed in transmission. The parallel and serial CRC generator unit was designed and functionality was verified by using Verilog language in Xilinx software. The CRC generator was designed using lookup table approach in pipeline method for calculating the bits information. The behaviour of
The linear feedback register was analysed with the help of simulation software. The parallel CRC generator addresses the issues of number of look up tables and critical path delays of various checkers in the polynomial expression. The folding, pipelining and retiming are the methods used for reducing the delay of the circuits without changing the functionality of the circuit and also maintaining the same throughput and date rate for digital communication. The three techniques are incorporated in parallel CRC generator for improving the throughput. The fast CRC address the issues of packet size and speed of transmission of bits. The mapping of a tri-level network into linear pipeline architecture for improving the throughput with the help of place and route approach of FPGA design. The each message bit rate was designed into number of execution units for reducing the latency. The hardware implementation for computing matrix in checksum was proposed and the data to be process in parallel manner. The parallel CRC generator process all the bits parallel with minimum number of cycles for less propagation delay and analysed in Verilog language using Xilinx software. This paper presents the implementation of CRC generator using area and power efficient gate Diffusion-Input (GDI) D flip flop. The basic configuration of GDI cell is shown in Figure 3.

![Fig. 3. GDI D Flip Flop with Buffer](image)

### 3.1. Types of errors caused by Radiation

Based on the particle strike the errors can be classified into hard error and soft errors the types of error depend on whether it is permanent damage or temporary damage. Single event upsets come under the clause of temporary damage or soft errors. The affected circuits can be recovered by using reset signals or by correction circuits. Hard errors are due to permanent damages. These errors cannot be corrected or the circuits cannot be recovered by correction mechanisms Single Event Burnout (SEB) , Single Event gate rupture ( SEGR) and single event latch up ( SEL) comes under this category. In this review we are going to review about the Single Event Upset which is soft error and which occurs in memories. These SEUs cause transient errors in combinational circuits and makes bit flips in sequential circuits. The CMOS SRAM basic cell is considered. An extensive study had been done with the detection and correction schemes for 6T SRAM cell. The similar simulations for CNTFET SRAM was done and compared with the same. Figure 1 shows the effect of single event upset in CNTFET SRAM.
4. SIMULATION AND IMPLEMENTATION

Detailed SPICE simulations were carried out on the proposed RHBD latch using advanced Predictive Technology Model (PTM) invented by the nano-scale Integration and Modeling (NIMO) Group of Arizona State University. As an evolution of raditional Berkeley Predictive Technology Model (BPTM), PTM of bulk CMOS is successfully generated for 130 to 32 nm technology nodes. The PTM can be easily customized to cover a wide range of process uncertainties. PTM is more physical, scalable, and continuous over technology generations and suitable for emerging variability and reliability issues. The 45 nm technology model card was chosen to perform the simulations. The proposed work was implemented in Xilinx using VHDL. Considering the stored 1 state (i.e., QN = 0, Q = 1, S0 = 0, and S1 = 1) for the proposed RHBD 12T cell. To write data 0 into the proposed 12T cell, word-lineWL and bitline BL need to be 0 state, and bitline BLN must be 1 state. Subsequently, node Q will be pulled down to 0 state, and node QN will be pulled up to 1 state.

4.1. SEU injection simulation

As mentioned in section 3, all the internal nodes were partitioned into different equivalent class of nodes so that SEU injection was only performed on three internal nodes from each equivalent class of nodes: {N1, N2} , {N4, N7} , { N3, N5, N6, N8, N9, N10} . SEU injection methodology is to simulate the high-energy particle striking. The current induced by SEU can be modeled as traditional double-exponential function current source, which can accurately represent the electrical impact of particle striking. The pulse can be expressed as

\[ I(t) = \frac{Q}{\tau_\alpha - \tau_\beta} (e^{-t/\tau_\alpha} - e^{-t/\tau_\beta}). \]

(a) Static reference latch; (b) TMR-latch
4.2. Delay and power comparison
The structure of the reference latch and TMR-latch. A performance comparison between the proposed latch, the reference latch and TMR-latch (note that the result is normalized by the reference latch), the propagation delay of the proposed latch is 83% of the TMR-latch, and the power dissipation of the proposed latch is 68% of the TMR-latch. In short, the simulation results reveal that the proposed latch is delay and power efficient in comparison with TMR-latch.

4.3. DICE Cell
As shown in Fig.1, the DICE cell uses twice the number of transistors of a standard storage cell. The DICE cell has two states, the 0 state (X1=0, X2=1, X3=0, X4=1) and the 1 state (X1=1, X2=0, X3=1, X4=0). In any of these two states upon the occurrence of a soft error (on a single node), the state of the node is always driven back to its original value. For example, in the 0 state, if the node struck by a particle is X2, the state of X2 goes from 1 to 0. However, this strike will not propagate along the feedback loop due to the interlocked configuration. Meanwhile, the state 0 stored in X1 can restore the state of X2; however, when a single event (strike) occurs on multiple nodes, the DICE cell is unable to drive back the original state. For example, in the 0 state, if the node struck by a particle is X2, the state of X2 goes from 1 to 0. Meanwhile, if node X1 is also affected by the strike, then it goes from 0 to 1. In this case, due to the strike on X1, the state of X2 will not be restored and a soft error is said to occur. Simulation results show that if there is a strike on X1, a very small amount of charge on X2 can change the state of the DICE cell.

Fig: DICE proposed cell

4.4. 12T Hardened Cell
A single node hardened memory cell has been proposed in. The basic storage element used in this memory cell relies on the hardening scheme of. In the memory cell its feedback loop is cut off by the transistors M5, M6, M7, and M8, i.e. for a single node upset, a transient pulse cannot be propagated along this loop back to its starting point. The gates of the PMOS and NMOS transistors are separated from the hardened nodes a1 and a2. Signal regeneration at a1 and a2 is controlled by the transistors M5 and M8. In this cell, the access pass gates (M1 and M2) are connected to node d instead of nodes a1 and a2 to prevent the high leakage current from BL to change the data stored in the memory cell. A TF on a1 or a2 will not change the data stored in the memory cell. A NMOS write control transistor is added to this memory cell for the write operation. As discussed in, a single ended SRAM cell
operates correctly when writing a “0” as data, but it may encounter problems when writing a “1”. Therefore, a write control transistor is added between M11 and ground to write a “1”. With this write control transistor, the hardened memory cell consists of eleven transistors, i.e. one transistor less than the DICE cell configuration. The 11T memory cell is unable to restore the state of the node when a single event causes a multiple node upset. Similar to the DICE cell, the 12T cell has two states, the 0 state (d=0, db=1, a1=1, a2=1) and the 1 state (d=1, db=0, a1=0, a2=0). If nodes a2 and d are affected by a strike, the state of the 11T memory cell will be changed, i.e. it has limited tolerance under a single event with a two node upset.

5. CONCLUSION
The proposed implementation of a novel radiation-hardened-by-design (RHBD) high speed CRC Generator architecture using gate diffusion input technique. The main objective of CRC generator is used for error detection in communication systems. The Gate Diffusion Input logic is a technique that is used to reduce transistor count and power consumption of sequential circuits. The hardware component of CRC is consists of group of D flip-flops. Here the gate diffusion input logic based D flip-flop is a basic cell to design a CRC Generator, maintaining low complexity of logic design. The proposed architecture is validated by Tanner EDA tool and implementation on Spartan 6 FPGA development board series.

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